
DISCRETE POWER DIODES and THYRISTORS

DATA BOOK



ST303C..C SERIES

INVERTER GRADE THYRISTORS

Puk Version

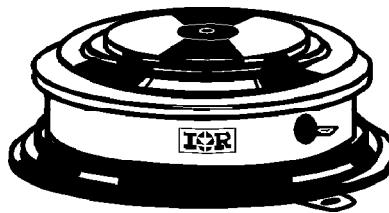
Features

- Metal case with ceramic insulator
- International standard case TO-200AB (E-PUK)
- All diffused design
- Center amplifying gate
- Guaranteed high dV/dt
- Guaranteed high dI/dt
- High surge current capability
- Low thermal impedance
- High speed performance

620A

Typical Applications

- Inverters
- Choppers
- Induction heating
- All types of force-commutated converters



case style TO-200AB (E-PUK)

Major Ratings and Characteristics

Parameters	ST303C..C	Units
$I_{T(AV)}$	620	A
@ T_{hs}	55	°C
$I_{T(RMS)}$	1180	A
@ T_{hs}	25	°C
I_{TSM}	7950	A
@ 50Hz	7950	A
@ 60Hz	8320	A
I^2t	316	KA ² s
@ 50Hz	316	KA ² s
@ 60Hz	289	KA ² s
V_{DRM}/V_{RRM}	400 to 1200	V
t_q range (*)	10 to 30	μs
T_J	- 40 to 125	°C

(*) $t_q = 10$ to $20\mu s$ for 400 to 800V devices

$t_q = 15$ to $30\mu s$ for 1000 to 1200V devices

ELECTRICAL SPECIFICATIONS

Voltage Ratings

Type number	Voltage Code	V_{DRM}/V_{RRM} , maximum repetitive peak voltage V	V_{RSM} , maximum non-repetitive peak voltage V	I_{DRM}/I_{RRM} max. @ $T_J = T_{J\max}$ mA
ST303C..C	04	400	500	50
	08	800	900	
	10	1000	1100	
	12	1200	1300	

Current Carrying Capability

Frequency				Units	
50Hz	1314	1130	2070	A	
400Hz	1260	1040	2190		
1000Hz	900	700	1900		
2500Hz	340	230	910		
Recovery voltage V_r	50	50	50	V	
Voltage before turn-on V_d	V_{DRM}		V_{DRM}		
Rise of on-state current di/dt	50	50	-	A/ μ s	
Heatsink temperature	40	55	40	55	°C
Equivalent values for RC circuit	$10\Omega / 0.47\mu F$		$10\Omega / 0.47\mu F$		$10\Omega / 0.47\mu F$

On-state Conduction

Parameter	ST303C..C	Units	Conditions			
$I_{T(AV)}$	Max. average on-state current	A	180° conduction, half sine wave double side (single side) cooled			
	@ Heatsink temperature	°C				
$I_{T(RMS)}$	Max. RMS on-state current	1180	DC @ 25°C heatsink temperature double side cooled			
I_{TSM}	Max. peak, one half cycle, non-repetitive surge current	7950	Sinusoidal half wave, Initial $T_J = T_{J\max}$			
		8320				
		6690				
		7000				
I^2t	Maximum I^2t for fusing	316	KA ² s	t = 10ms	No voltage reapplied	Initial $T_J = T_{J\max}$
		289		t = 8.3ms	No voltage reapplied	
		224		t = 10ms	100% V_{RRM} reapplied	
		204		t = 8.3ms	100% V_{RRM} reapplied	
$I^2\sqrt{t}$	Maximum $I^2\sqrt{t}$ for fusing	3160	KA ² /s	t = 0.1 to 10ms, no voltage reapplied		

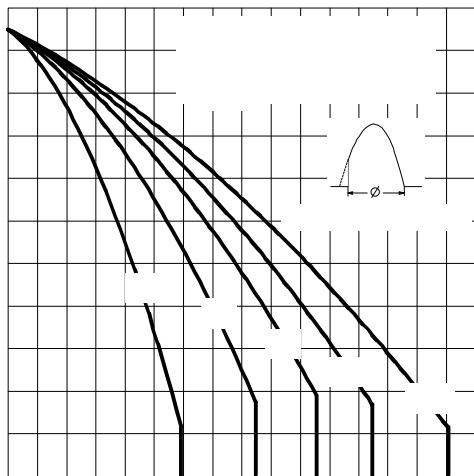


Fig. 3 - Current Ratings Characteristics

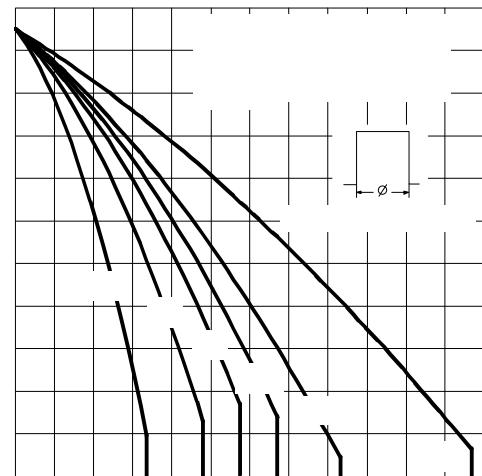


Fig. 4 - Current Ratings Characteristics

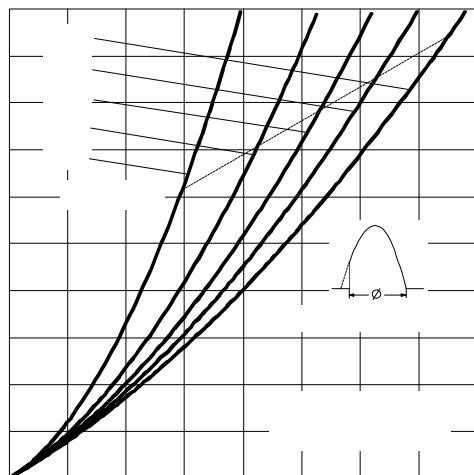


Fig. 5 - On-state Power Loss Characteristics

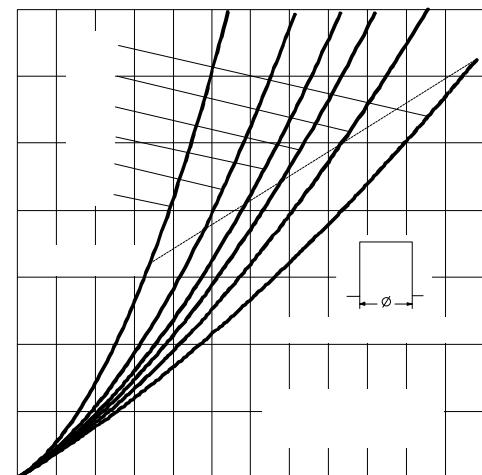


Fig. 6 - On-state Power Loss Characteristics

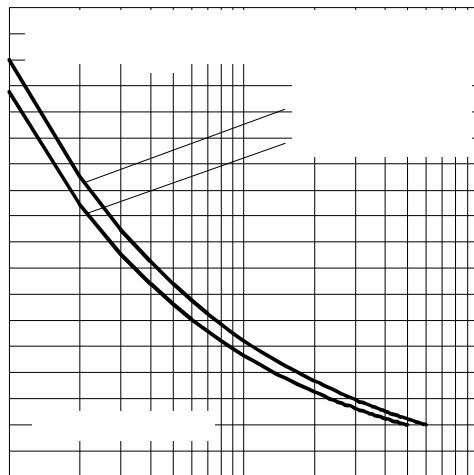


Fig. 7 - Maximum Non-repetitive Surge Current

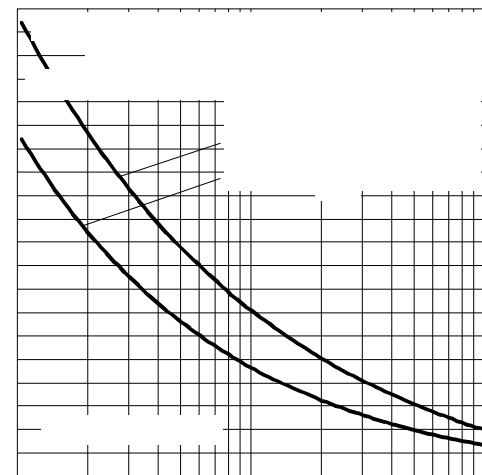


Fig. 8 - Maximum Non-repetitive Surge Current

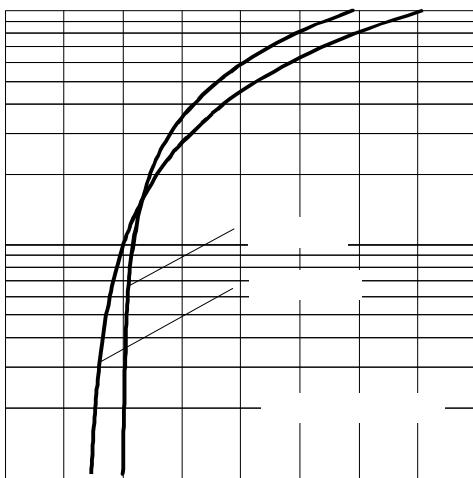


Fig. 9 - On-state Voltage Drop Characteristics

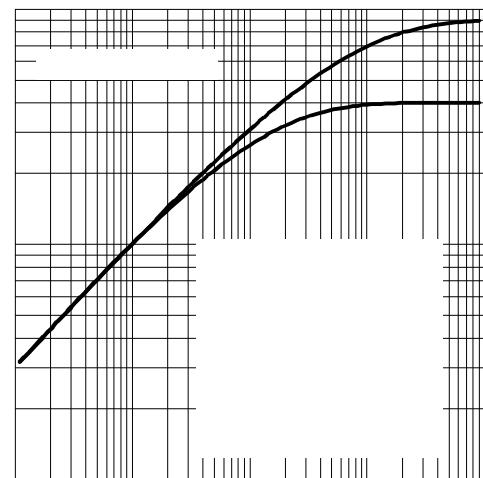
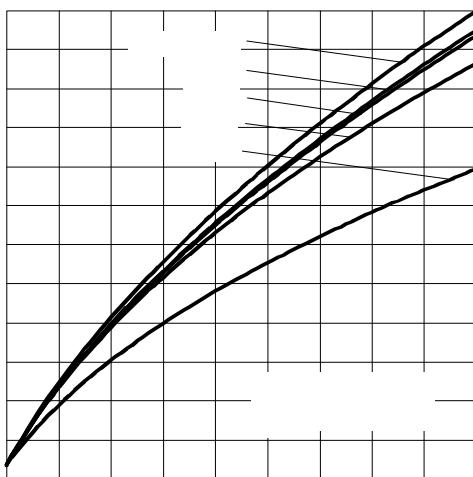
Fig. 10 - Thermal Impedance Z_{thJ-hs} Characteristics

Fig. 11 - Reverse Recovered Charge Characteristics

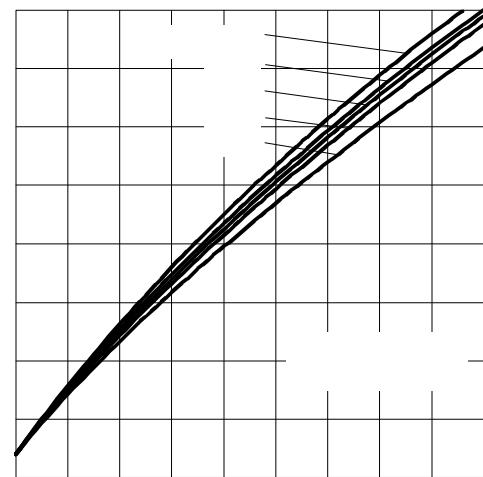


Fig. 12 - Reverse Recovery Current Characteristics

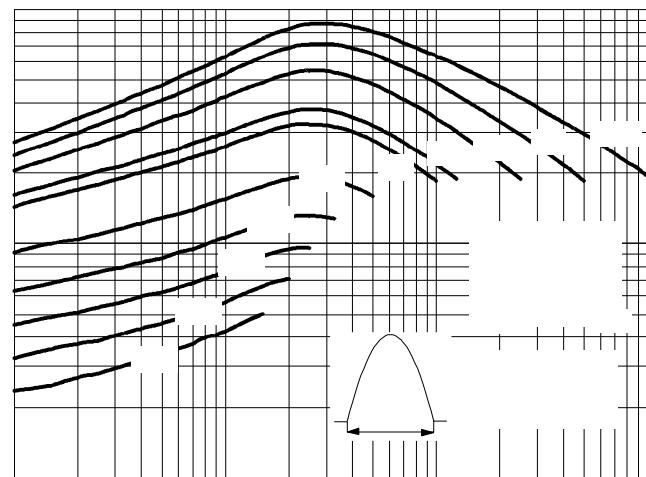
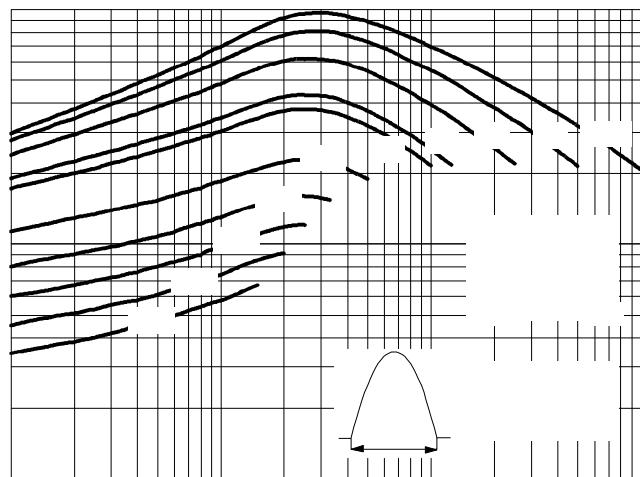


Fig. 13 - Frequency Characteristics

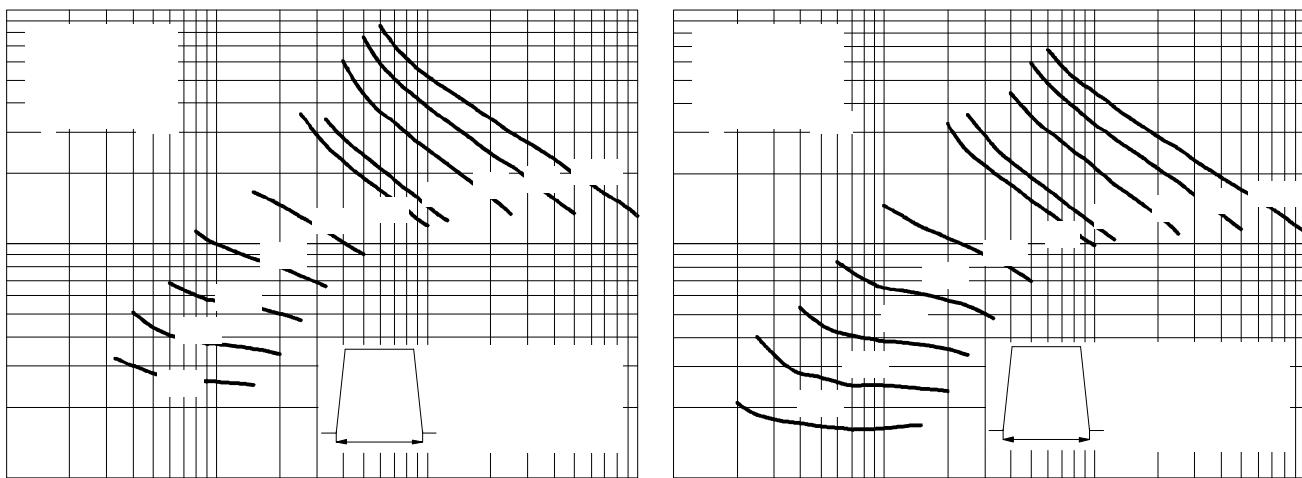


Fig. 14 - Frequency Characteristics

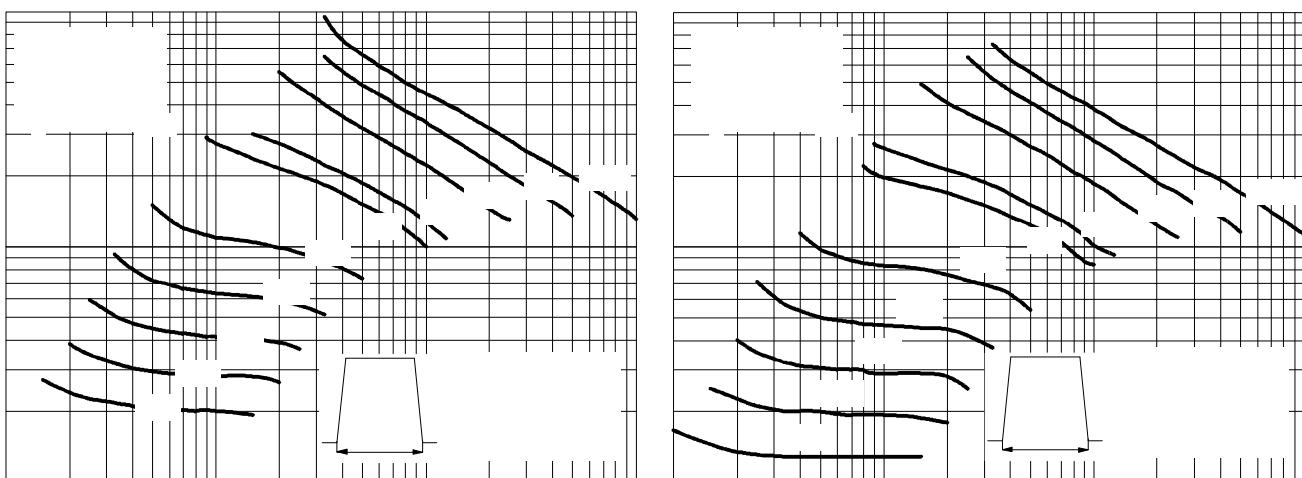


Fig. 15 - Frequency Characteristics

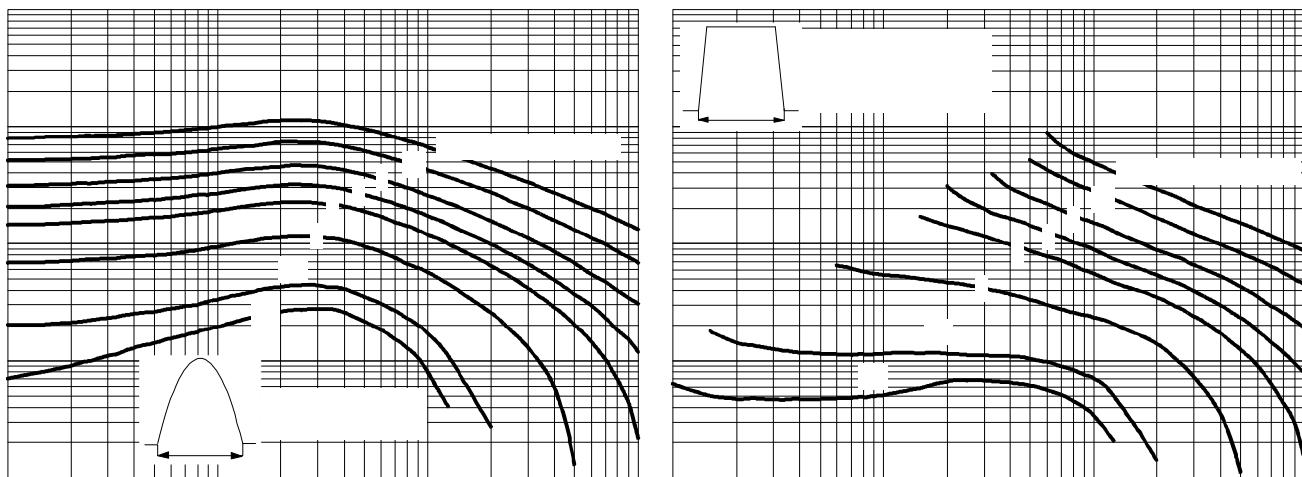


Fig. 16 - Maximum On-state Energy Power Loss Characteristics

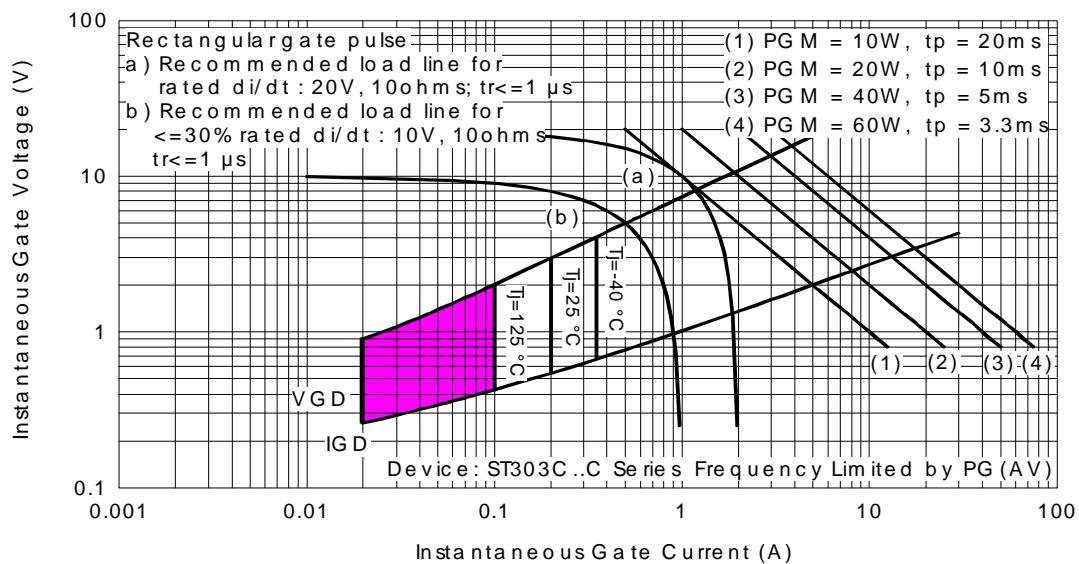


Fig. 17 - Gate Characteristics

On-state Conduction

Parameter	ST303C..C	Units	Conditions	
V_{TM}	Max. peak on-state voltage	2.16	V	$I_{TM} = 1255A, T_J = T_J \text{ max}, t_p = 10\text{ms sine wave pulse}$
$V_{T(TO)1}$	Low level value of threshold voltage	1.44		$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
$V_{T(TO)2}$	High level value of threshold voltage	1.48		$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
r_{t1}	Low level value of forward slope resistance	0.57	$\text{m}\Omega$	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
r_{t2}	High level value of forward slope resistance	0.56		$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
I_H	Maximum holding current	600	mA	$T_J = 25^\circ\text{C}, I_T > 30\text{A}$
I_L	Typical latching current	1000		$T_J = 25^\circ\text{C}, V_A = 12\text{V}, R_a = 6\Omega, I_G = 1\text{A}$

Switching

Parameter	ST303C..C	Units	Conditions	
di/dt	Max. non-repetitive rate of rise of turned-on current	1000	$T_J = T_J \text{ max}, V_{DRM} = \text{rated } V_{DRM}$ $I_{TM} = 2 \times di/dt$	
t_d	Typical delay time	0.83	μs	$T_J = 25^\circ\text{C}, V_{DM} = \text{rated } V_{DRM}, I_{TM} = 50\text{A DC}, t_p = 1\mu\text{s}$ Resistive load, Gate pulse: 10V, 5Ω source
t_q	Max. turn-off time (*)	Min 10 Max 30		$T_J = T_J \text{ max}, I_{TM} = 550\text{A}, \text{commutating } di/dt = 40\text{A}/\mu\text{s}$ $V_R = 50\text{V}, t_p = 500\mu\text{s}, dv/dt: \text{see table in device code}$

(*) $t_q = 10$ to $20\mu\text{s}$ for 400 to 800V devices; $t_q = 15$ to $30\mu\text{s}$ for 1000 to 1200V devices.

Blocking

Parameter	ST303C..C	Units	Conditions
dv/dt	Maximum critical rate of rise of off-state voltage	500	$T_J = T_J \text{ max. linear to } 80\% V_{DRM}, \text{higher value available on request}$
I_{RRM} I_{DRM}	Max. peak reverse and off-state leakage current	50	$T_J = T_J \text{ max, rated } V_{DRM}/V_{RRM} \text{ applied}$

Triggering

Parameter	ST303C..C	Units	Conditions	
P_{GM}	Maximum peak gate power	60	W	$T_J = T_J \text{ max, } f = 50\text{Hz, d\% = 50}$
$P_{G(AV)}$	Maximum average gate power	10		
I_{GM}	Max. peak positive gate current	10	A	$T_J = T_J \text{ max, } t_p \leq 5\text{ms}$
$+V_{GM}$	Maximum peak positive gate voltage	20		
$-V_{GM}$	Maximum peak negative gate voltage	5	V	$T_J = T_J \text{ max, } t_p \leq 5\text{ms}$
I_{GT}	Max. DC gate current required to trigger	200		
V_{GT}	Max. DC gate voltage required to trigger	3	V	$T_J = 25^\circ\text{C}, V_A = 12\text{V, Ra = 6\Omega}$
I_{GD}	Max. DC gate current not to trigger	20		
V_{GD}	Max. DC gate voltage not to trigger	0.25	V	$T_J = T_J \text{ max, rated } V_{DRM} \text{ applied}$

ST303C..C Series

Thermal and Mechanical Specification

Parameter	ST303C..C	Units	Conditions
T_J	Max. operating temperature range	-40 to 125	°C
T_{stg}	Max. storage temperature range	-40 to 150	
R_{thJ-hs}	Max. thermal resistance, junction to heatsink	0.09 0.04	K/W K/W
R_{thC-hs}	Max. thermal resistance, case to heatsink	0.020 0.010	K/W K/W
F	Mounting force, ± 10%	9800 (1000)	N (Kg)
wt	Approximate weight	83	g
Case style	TO - 200AB (E-PUK)	See Outline Table	

ΔR_{thJ-hs} Conduction

(The following table shows the increment of thermal resistance R_{thJ-hs} when devices operate at different conduction angles than DC)

Conduction angle	Sinusoidal conduction		Rectangular conduction		Units	Conditions
	Single Side	Double Side	Single Side	Double Side		
180°	0.010	0.010	0.007	0.007	K/W	$T_J = T_{J \text{ max.}}$
120°	0.012	0.012	0.012	0.013		
90°	0.015	0.015	0.016	0.017		
60°	0.022	0.022	0.023	0.023		
30°	0.036	0.036	0.036	0.037		

Ordering Information Table

Device Code	ST	30	3	C	12	C	H	K	1	
	1	2	3	4	5	6	7	8	9	10
1	- Thyristor									
2	- Essential part number									
3	- 3 = Fast turn off									
4	- C = Ceramic Puk									
5	- Voltage code: Code x 100 = V_{RRM} (See Voltage Rating Table)									
6	- C = Puk Case TO-200AB (E-PUK)									
7	- Reapplied dv/dt code (for t_q test condition)									
8	- t_q code _____									
9	- 0 = Eyelet term. (Gate and Aux. Cathode Unsoldered Leads)									
10	- Critical dv/dt:									
	None = 500V/μsec (Standard value)									
	L = 1000V/μsec (Special selection)									

dv/dt - t_q combinations available						
	dv/dt (V/μs)	20	50	100	200	400
t_q (μs)	10	CN	DN	EN	FN *	HN
	12	CM	DM	EM	FM	HM
up to 800V	15	CL	DL	EL	FL *	HL
	20	CK	DK	EK	FK *	HK
t_q (μs)	15	CL	--	--	--	--
	18	CP	--	--	--	--
only for	20	CK	DK	EK	FK *	HK
1000/1200V	25	CJ	DJ	EJ	FJ *	HJ
	30	--	DH	EH	FH	HH

*Standard part number.
All other types available only on request.

Outline Table

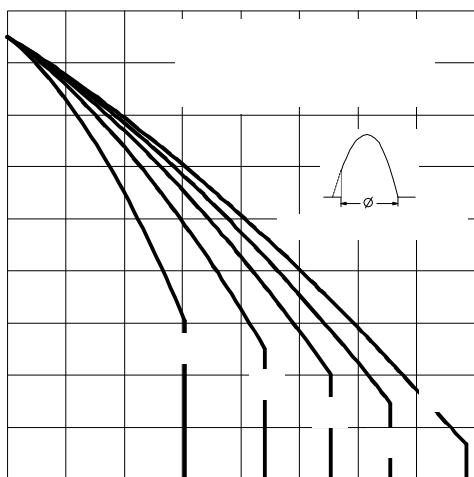
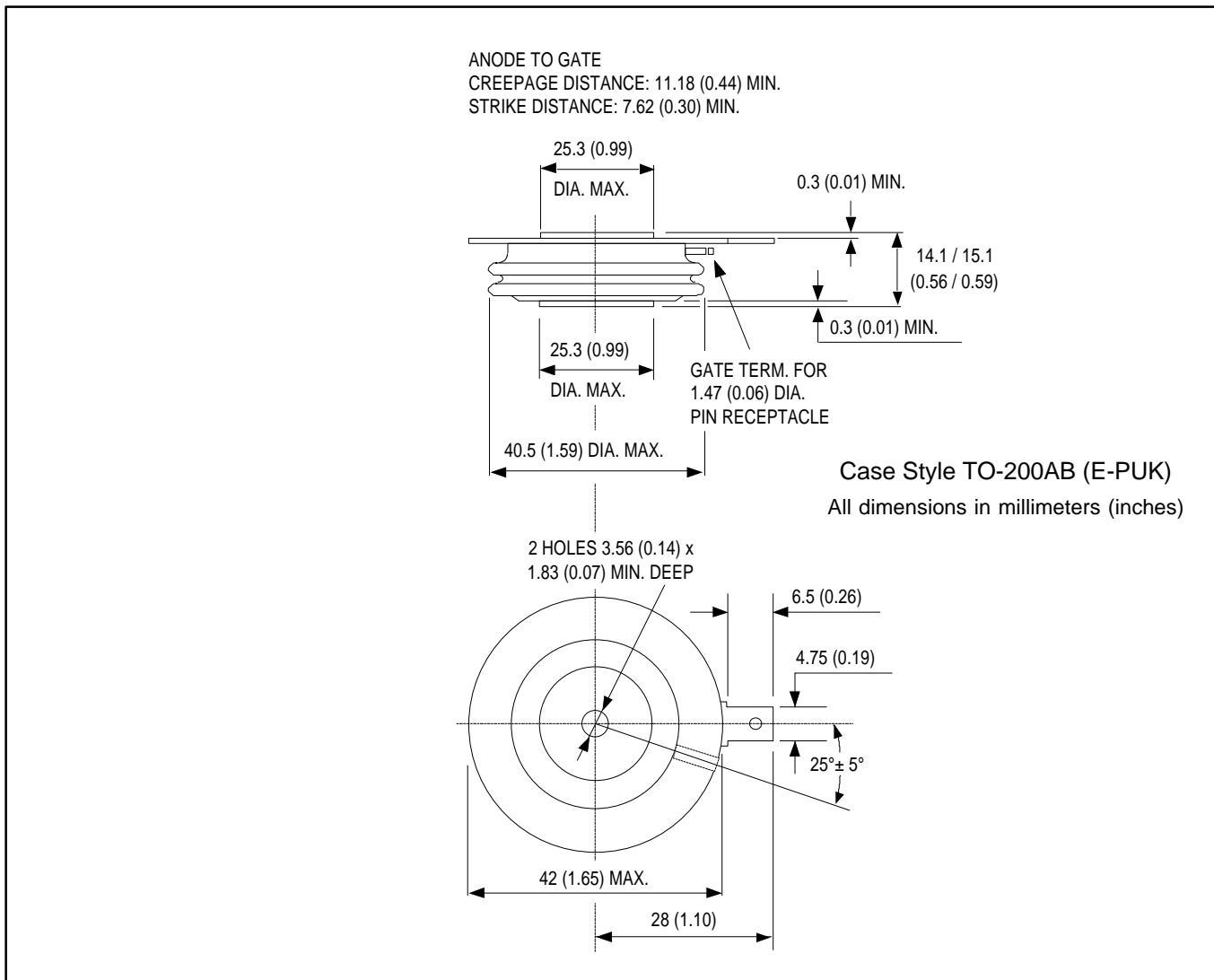


Fig. 1 - Current Ratings Characteristics

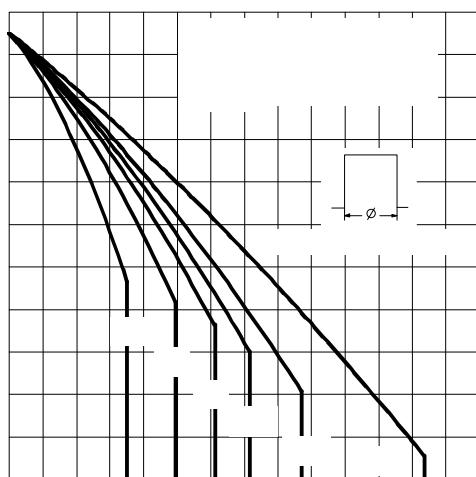


Fig. 2 - Current Ratings Characteristics